



Chiu Sheung School, Hong Kong
79B Pok Fu Lam Road, Hong Kong
Tel : 2546-1644 Fax : 2517-2483
Website : www.csshk.edu.hk

12th December, 2022

Dear Parents/Guardians,

Notice on "Establishment of parent account of SSPA e-Platform" 2022-2023 No.117B

(To: P.6 parents)

In line with the Smart Government strategy, the EDB will implement digitalisation of S1 admissions starting from 2023. Parents can log-in to the "Secondary School Places Allocation (SSPA) e-Platform" from 6th December, 2022.

Overview of the SSPA e-Platform:

After registering as a user of the SSPA e-Platform, parents' permissions are divided into two categories:

Category 1: Binding an account with " iAM Smart+ ", you can submit applications for Discretionary Places (DPs) for your children through the e-Platform and receive notification (if applicable) of allotted places, submitting Central Allocation applications and receiving allocation results.

Category 2: Binding the account with " iAM Smart " to receive notifications (if applicable) of allotted places of Discretionary Places (DPs) application and the allocation results.

Submission of application of SSPA:

Method 1: Paper application

Method 2: If parents have registered as users of SSPA e-Platform and bind the account with " iAM Smart+ ", they can Submit the application through the SSPA e-Platform.

To understand more on the SSPA application procedures, parents can visit the Education Bureau website (<http://www.edb.gov.hk>) or scan the attached QR code for details.

Please sign the reply slip and return it to the class teacher before 14th December.

Mr. Chim Hon Ming,
Principal, CSSHK

✂-----
To: CSSHK Class No:()

Reply slip on "Establishment of parent account of SSPA e-Platform" 2022-2023 No.117B

I acknowledge receipt of the notice and understand its content, I

- will choose to submit the SSPA application through the SSPA e-Platform and register and open the e-account before 20/12/2022.
- will choose to submit the SSPA application by paper form.

Name of student: _____ Class: _____

Name of parent: _____ Signature: _____

Contact Number: _____

Please "✓" the appropriate box.

14-12-2022 Ting

Attachment :

SSPA e-Platform Secondary School Places Allocation (SSPA) 2021/2023
(<https://esspa.edb.gov.hk/>)



iAM Smart
(<https://www.iamsmart.gov.hk/en/>)



SSPA e-Platform Parent's Guide
(https://www.edb.gov.hk/en/edu-system/primary-secondary/spa-systems/secondary-spa/general-info/sspa_eplatform_parents_guide.html)

